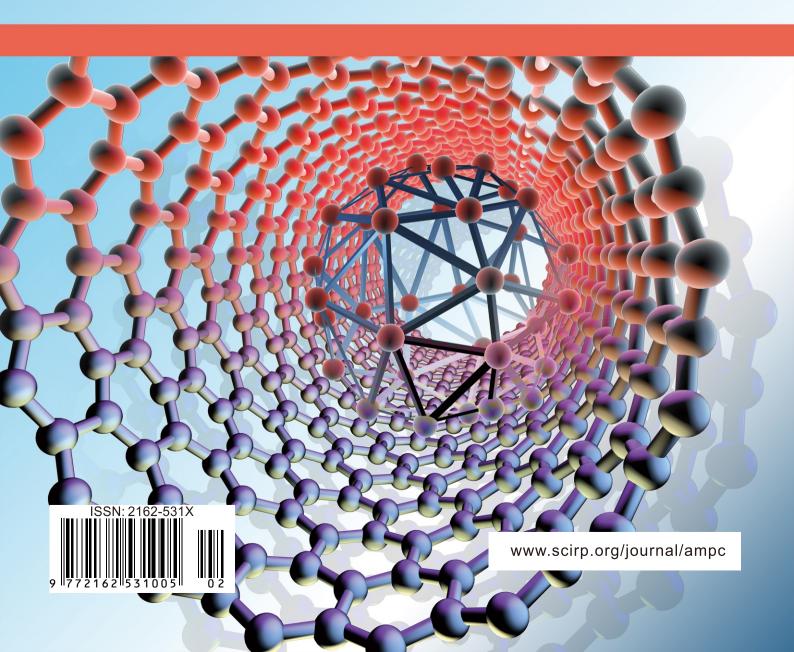


Advances in Materials Physics and Chemistry



Journal Editorial Board

ISSN: 2162-531X (Print) ISSN: 2162-5328 (Online) http://www.scirp.org/journal/ampc

......

Editor-in-Chief

Prof. Zhiwen Chen Shanghai University, China

Editorial Board

Dr. Bensely AlbertCMC Americas, Inc., USAProf. Adriana BigiUniversity of Bologna, Italy

Dr. Mary Caruso 3M Company, USA

Prof. Changle Chen University of Science & Technology of China, China

Dr. Tien-Min Gabriel Chu Indiana University School of Dentistry, USA

Dr. Byron D. Gates Simon Fraser University, Canada

Dr. A. Nirmala Grace VIT University, India

Prof. David Hui University of New Orleans, USA

Prof. Kisuk Kang Seoul National University, South Korea

Dr. Hong Jin Kim Advanced Module Engineering, Globalfoundries, USA

Dr. Ing Kong RMIT University, Malaysia

Dr. Mathew T. Mathew Rush University Medical Centre, USA

Dr. Santosh K. Pandey Iowa State University, USA

Prof. Rakesh Sharma FAMU-FSU College of Engineering, USA

Prof. Peter E. Strizhak

National Academy of Sciences of Ukraine, Ukraine

Dr. Yadong Wang

University of Pittsburgh School of Medicine, USA

Dr. Meng ZhangPhilips Lumileds Lighting Company, USAProf. Qifa ZhouUniversity of Southern California, USA



Volume 8 Number 2

ISSN Online: 2162-5328 ISSN Print: 2162-531X

February 2018

Table of Contents

The Role of the Chelating Agent on the Structure and Anticorrosion Performances of
an Organosilane—Zirconium Sol-Gel Coatings
M. O'Sullivan, N. A. Odewunmi, M. Cullen, A. A. Sorour, B. Duffy, Z. M. Gasem, M. Oubaha89

Advances in Materials Physics and Chemistry (AMPC) Journal Information

SUBSCRIPTIONS

The Advances in Materials Physics and Chemistry (Online at Scientific Research Publishing, www.SciRP.org) is published monthly by Scientific Research Publishing, Inc., USA.

Subscription rates:

Print: \$79 per issue.

To subscribe, please contact Journals Subscriptions Department, E-mail: sub@scirp.org

SERVICES

Advertisements

Advertisement Sales Department, E-mail: service@scirp.org

Reprints (minimum quantity 100 copies)

Reprints Co-ordinator, Scientific Research Publishing, Inc., USA.

E-mail: sub@scirp.org

COPYRIGHT

Copyright and reuse rights for the front matter of the journal:

Copyright © 2018 by Scientific Research Publishing Inc.

This work is licensed under the Creative Commons Attribution International License (CC BY).

http://creativecommons.org/licenses/by/4.0/

Copyright for individual papers of the journal:

Copyright © 2018 by author(s) and Scientific Research Publishing Inc.

Reuse rights for individual papers:

Note: At SCIRP authors can choose between CC BY and CC BY-NC. Please consult each paper for its reuse rights.

Disclaimer of liability

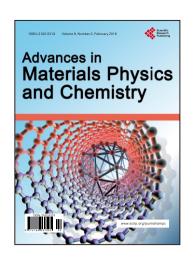
Statements and opinions expressed in the articles and communications are those of the individual contributors and not the statements and opinion of Scientific Research Publishing, Inc. We assume no responsibility or liability for any damage or injury to persons or property arising out of the use of any materials, instructions, methods or ideas contained herein. We expressly disclaim any implied warranties of merchantability or fitness for a particular purpose. If expert assistance is required, the services of a competent professional person should be sought.

PRODUCTION INFORMATION

For manuscripts that have been accepted for publication, please contact:

E-mail: ampc@scirp.org





Advances in Materials Physics and Chemistry

ISSN: 2162-531X (Print) ISSN: 2162-5328 (Online)

http://www.scirp.org/journal/ampc

Advances in Materials Physics and Chemistry contains rapid communications, full-length original research, review articles and comments on interrelationships among synthesis, micro/nanostructures, properties, processing and performance of Materials Science, Physics, and Chemistry. This includes, but is not limited to:

- Biomaterials
- Composite Materials
- Energy Resources Materials
- Environmental Materials
- Fine Ceramics
- Graphene and Carbon
- Magnetics
- Nanodevices
- Nanomaterials
- Nanotechnology
- **Optoelectronic Materials**
- **Polymers**
- Quantum Science and Technology
- Semiconductors
- Superconductors
- Surface and Interface Science
- Thin Films

Editor-in-Chief

Prof. Zhiwen Chen Shanghai University, China

Editorial Board

Dr. A. Nirmala Grace

Dr. Bensely Albert Prof. David Hui Prof. Adriana Bigi Prof. Kisuk Kang Dr. Mary Caruso Dr. Hong Jin Kim Prof. Changle Chen Dr. Ing Kong Dr. Tien-Min Gabriel Chu Dr. Byron D. Gates

Dr. Mathew T. Mathew Dr. Santosh K. Pandey Prof. Rakesh Sharma

Prof. Peter E. Strizhak Dr. Yadong Wang Dr. Meng Zhang Prof. Qifa Zhou

Website and E-Mail

http://www.scirp.org/journal/ampc E-mail: ampc@scirp.org

What is SCIRP?

Scientific Research Publishing (SCIRP) is one of the largest Open Access journal publishers. It is currently publishing more than 200 open access, online, peer-reviewed journals covering a wide range of academic disciplines. SCIRP serves the worldwide academic communities and contributes to the progress and application of science with its publication.

What is Open Access?

All original research papers published by SCIRP are made freely and permanently accessible online immediately upon publication. To be able to provide open access journals, SCIRP defrays operation costs from authors and subscription charges only for its printed version. Open access publishing allows an immediate, worldwide, barrier-free, open access to the full text of research papers, which is in the best interests of the scientific community.

- High visibility for maximum global exposure with open access publishing model
- Rigorous peer review of research papers
- Prompt faster publication with less cost
- Guaranteed targeted, multidisciplinary audience





Website: http://www.scirp.org Subscription: sub@scirp.org Advertisement: service@scirp.org